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Application Number	10645047
Filing Date	2003-08-21
First Named Inventor	Sampath Purushothaman et al.
Art Unit	2822
Examiner Name	David E. Graybill
Attorney Docket Number	YOR920030029US2 (16841)

U.S. PATENTS

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/DG/	2	5114754		1992-05-19	Cronin et al.	
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/DG/	2	PRASAD, K. ET AL., Multilevel Thin Film Packaging: Applications and Processes for High Performance Systems, Trans. Comp. Pac. Man. Tech. - Pt. B: Adv. Pac., IEEE, February 1994, pp. 38-49, Vol. 17, No. 1	<input type="checkbox"/>
/DG/	3	SHIH, D.-Y. ET AL., Cu Passivation: A Method of Inhibiting Copper-Polyamic Acid Interactions, Appl. Phys. Lett., September 16, 1991, pp. 1424-1426, Vol. 59, No. 12	<input type="checkbox"/>
/DG/	4	OHUCHI, F. S. ET AL., Summary Abstract: Ti as a Diffusion Barrier Between Cu and Polyimide, J. Vac. Sci. Technol. A, May/June 1988, pp. 1004-1006, Vol. 6, No. 3	<input type="checkbox"/>
/DG/	5	O'SULLIVAN, E. J. ET AL., Electrolessly Deposited Diffusion Barriers for Microelectronics, IBM J. Res. Develop., September 1998, pp. 607-620, Vol. 42, N. 5	<input type="checkbox"/>
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/DG/	9	LEE, K.-W. ET AL., Adhesion of Poly(arylene ether benzimidazole) to Copper and Polyimides, J. Adhesion Sci. Technol., 1996, pp. 807-821, Vol. 10, No. 9	<input type="checkbox"/>

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/DG/	10	MATIENZO, LUIS J. ET AL., Adhesion of Metal Films to Polyimides, IBM Corp., Endicott, NY	<input type="checkbox"/>
/DG/	11	LINDE, H. G., Adhesive Interface Interactions Between Primary Aliphatic Amine Surface Conditioners and Polyamic Acid/Polyimide Resins, J. Poly. Sci.: Poly. Chem. Ed., 1982, pp. 1031-1041, Vol. 20	<input type="checkbox"/>

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